

Around 1977

Development of packages for EPROM

~ Packaging ~

Around 1977, EPROM was developed by Intel, in which electrons are stored in the transfer gate formed under the MOSFET gate, and the data is erased by UV irradiation.

Musashi Works of Hitachi developed various types of packages for EPROM, such as DILC type and LCC type packages which were sealed with a sapphire plate that was transparent alumina having the same linear expansion coefficient as that of ceramic package substrate, sealed by the low melting point glass, DILG type having a transparent window formed on the cap, a ceramic type package with transparent window for a PoP structure to socket mount EPROM on a microprocessor, and for a microprocessor with built-in EPROM.

The first DILC product was HN462708. The pictures below show this device, the center one is a PoP type with EPROM mounted on a microprocessor, and the right one is a on-chip EPROM microprocessor assembled in 64-pin side-blazed ceramic package with a transparent window sealed by low melting point glass.

